

DOCKET NO.: 295958US0PCT/sal

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF:

Hideo AOKI, et al.

GROUP: 1796

SERIAL NO: 10/591,455

FILED: January 18, 2007

EXAMINER: BUTTNER, D. J.

FOR: THERMOPLASTIC RESIN COMPOSITION AND MOLDED ARTICLE  
COMPRISING THE SAME

**SUBMISSION OF SUPPLEMENTAL APPLICATION DATA SHEET**

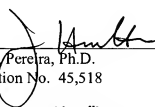
Office of Initial Patent Examination  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Applicant(s) submit herewith a Supplemental Application Data Sheet for the above-identified application for the purpose of correcting the Application date which appears incorrect on the Supplemental Application Data Sheet (Filed January 18, 2007).

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.  
Norman F. Oblon



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Daniel J. Pereira, Ph.D.  
Registration No. 45,518

Customer Number

**22850**

Tel. (703) 413-3000  
Fax. (703) 413-2220  
(OSMMN 06/04)

**James D. Hamilton**  
**Registration No. 28,421**